

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1-8. (canceled)

9. (currently amended) A semiconductor device comprising:

a first conductor including a first portion, a second portion having a first terminal surface, and a third portion connecting the first portion and the second portion;

a second conductor placed by in side-by-side relationship to the second portion, including a second terminal surface facing in a same direction as does the first terminal surface;

a semiconductor chip including a first surface and a second surface away from the first surface, the first surface being provided with a first electrode electrically connected with the first portion, the second surface being provided with a second electrode electrically connected with the second conductor, the semiconductor chip being bonded to the second conductor via the second surface; and

a resin package sealing the first conductor, the second conductor and the semiconductor chip while exposing the first terminal surface and the second terminal surface;

wherein the first portion and the third portion share a bent first border region, the second portion and the third portion sharing a bent second border region,

~~wherein the third portion is smaller than the first portion in width at the first border region, or the third portion is smaller than the second portion in width at the second border region, and~~

wherein the second portion has a first edge located adjacent to the third portion and a second edge opposite to the first edge, the second portion being provided with a pair of cutouts extending from the first edge toward the second edge to partially define the third portion.

10. (original) The semiconductor device according to Claim 9, wherein the first conductor has a shape of letter J, U or C, enclosing at least part of the semiconductor chip.

11. (original) The semiconductor device according to Claim 9, wherein the first portion of the first conductor entirely covers the first surface of the semiconductor chip and is bonded to the semiconductor chip.

12-17. (canceled)